

Effectiveness of Grown Poly(methyl methacrylate)/PMMA Brush as a Masking Agent

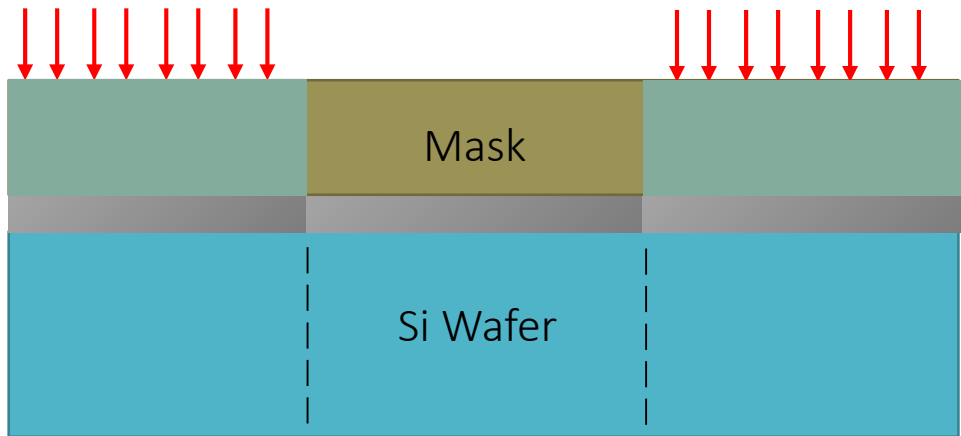
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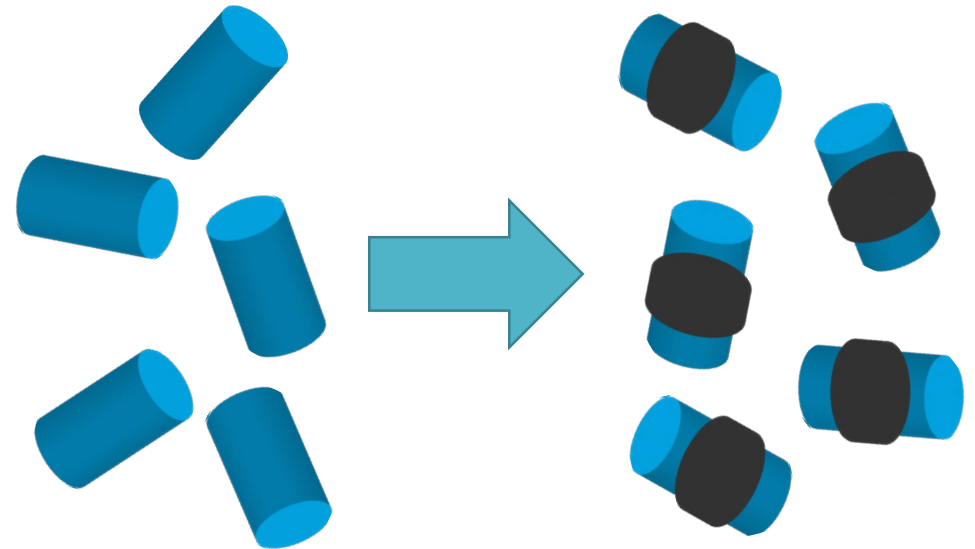


2D vs 3D Fabrication



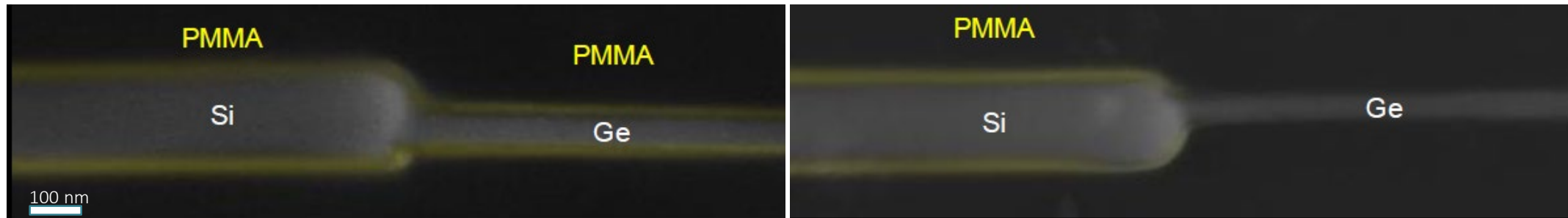
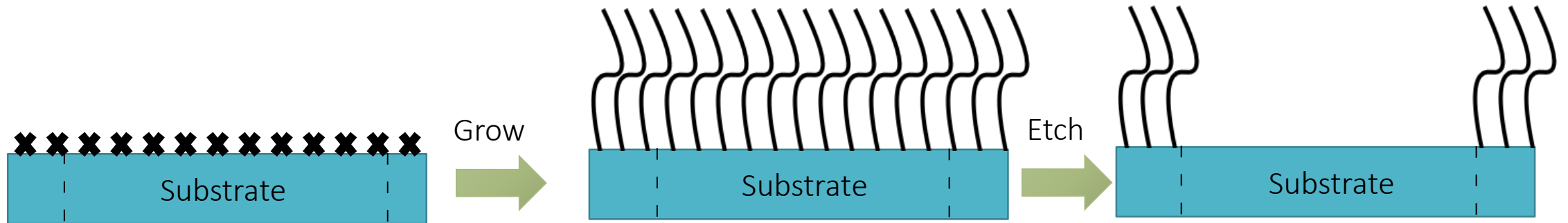
Etching
Top-Down

Difficult to make nanostructures in 3D

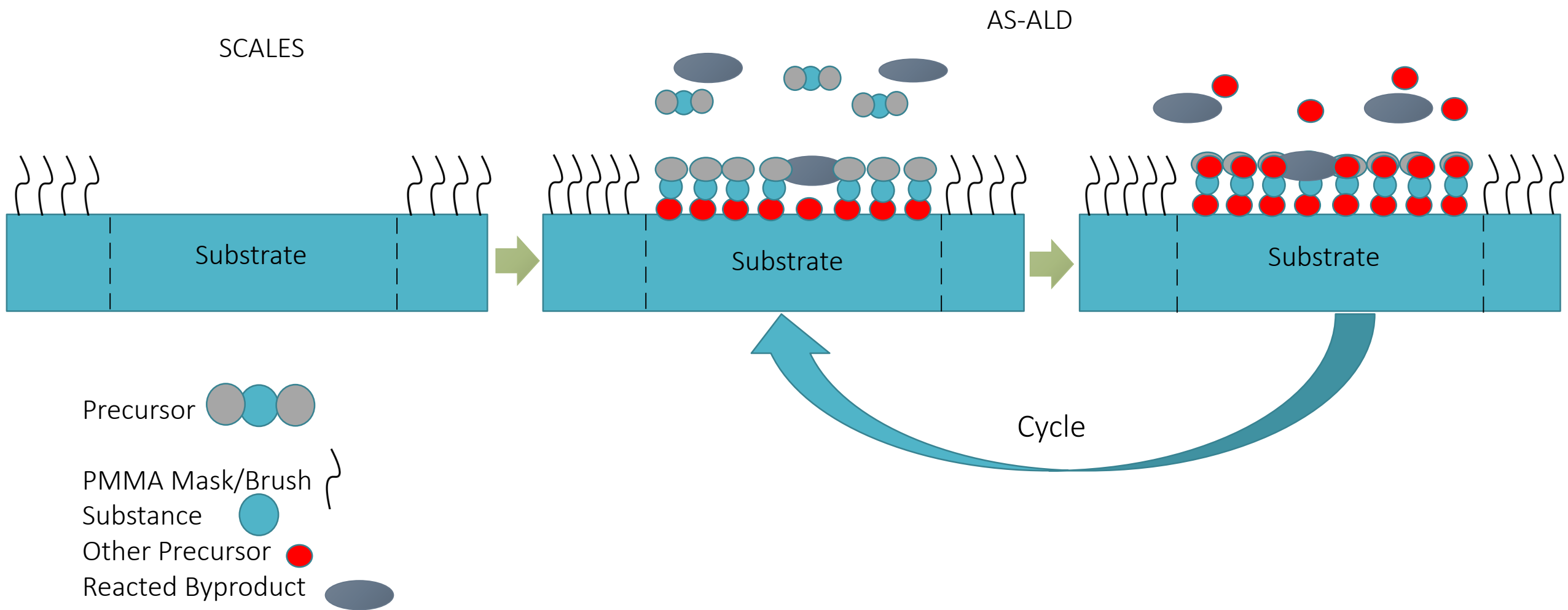


Selective CoAxial Lithography via Etching of Surfaces (SCALES) Process¹

- Lead to Fully Bottom-Up Fabrication Process
 - Polymerization from surface of nanostructure via atom transfer radical polymerization



Area-Selective Atomic Layer Deposition (AS-ALD)



Grown PMMA Brush as an Effective Mask

Goal: To investigate and optimize the masking ability of grown PMMA brush

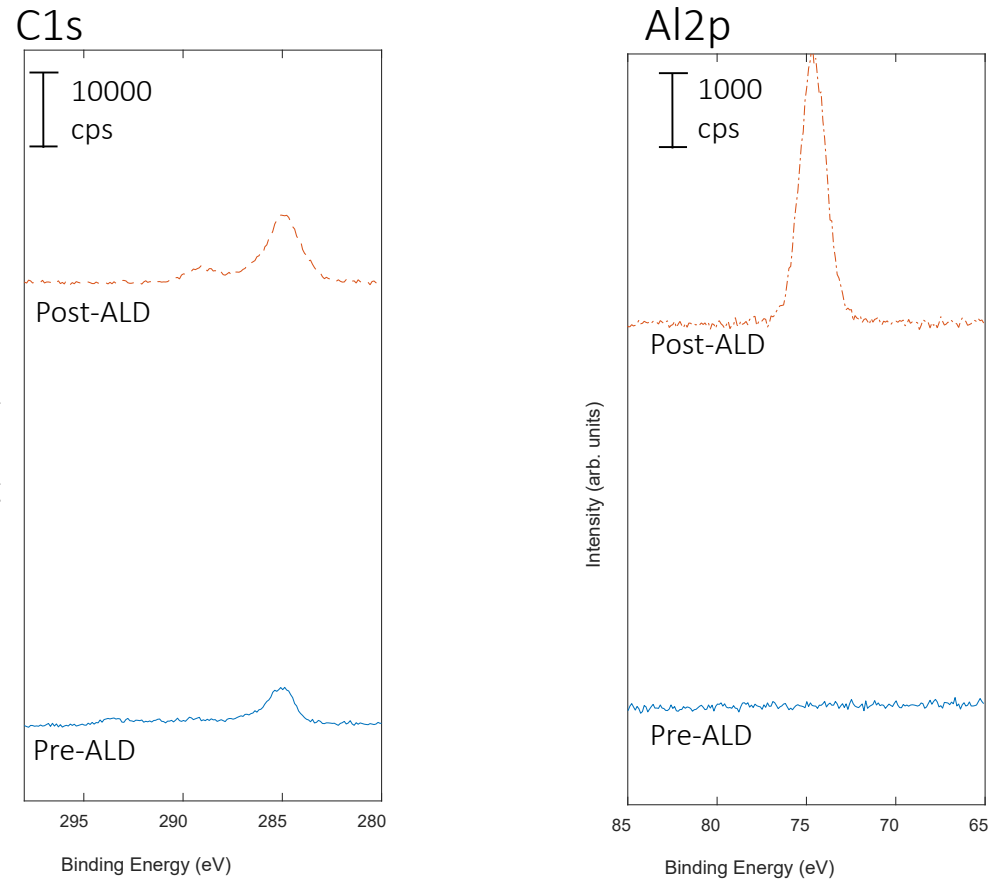
Focus is on the AS-ALD step after SCALES

- See if grown PMMA brush prevents ALD on covered areas
- Process specifications of ALD which affect masking abilities
- Want to be able to selectively remove mask and not deposited material

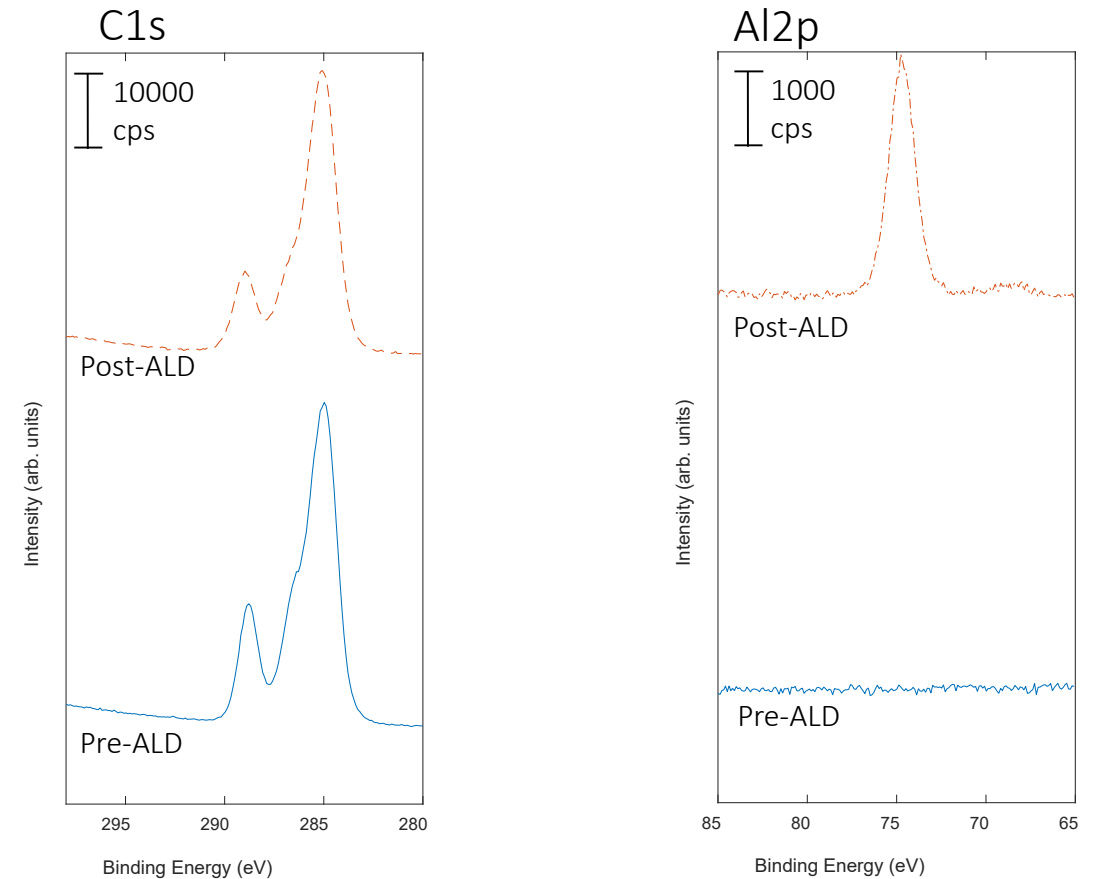
Experimental Overview

- Performed 10 cycles ALD on Si wafers and Si w/PMMA (~30nm grown)

Bare Si

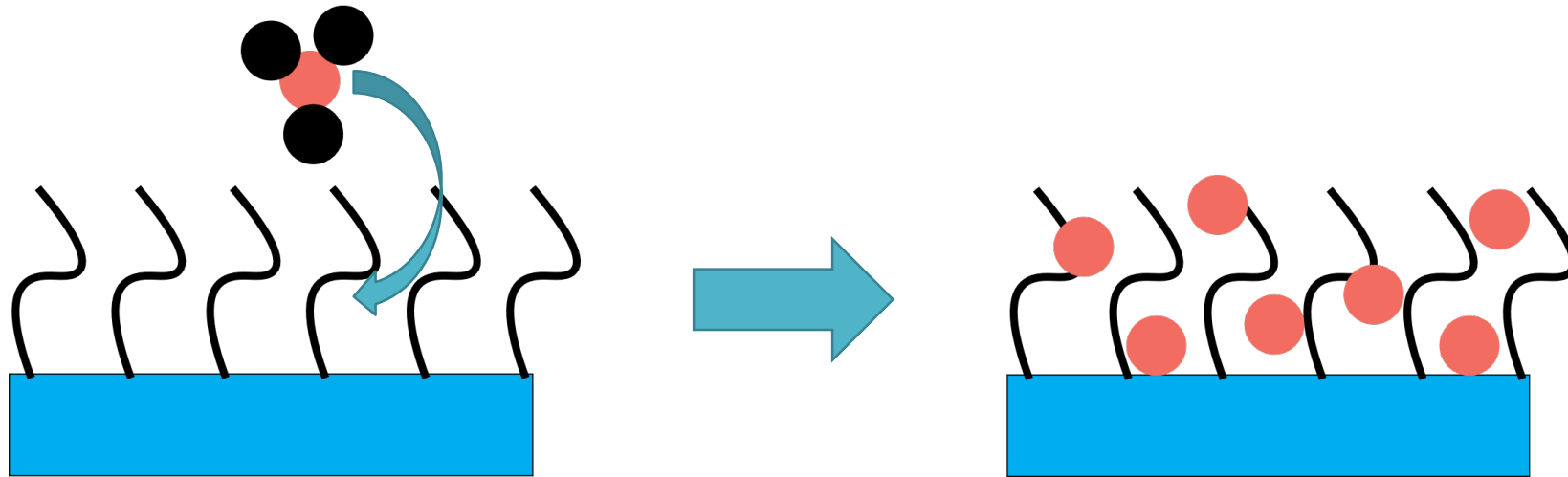


PMMA

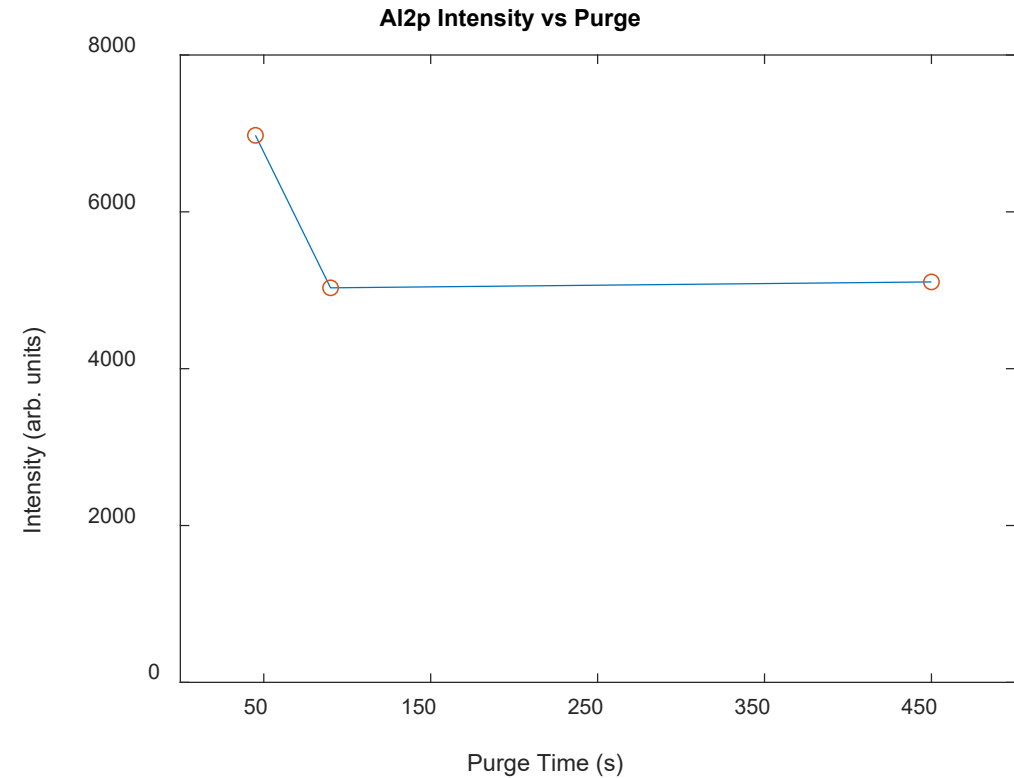
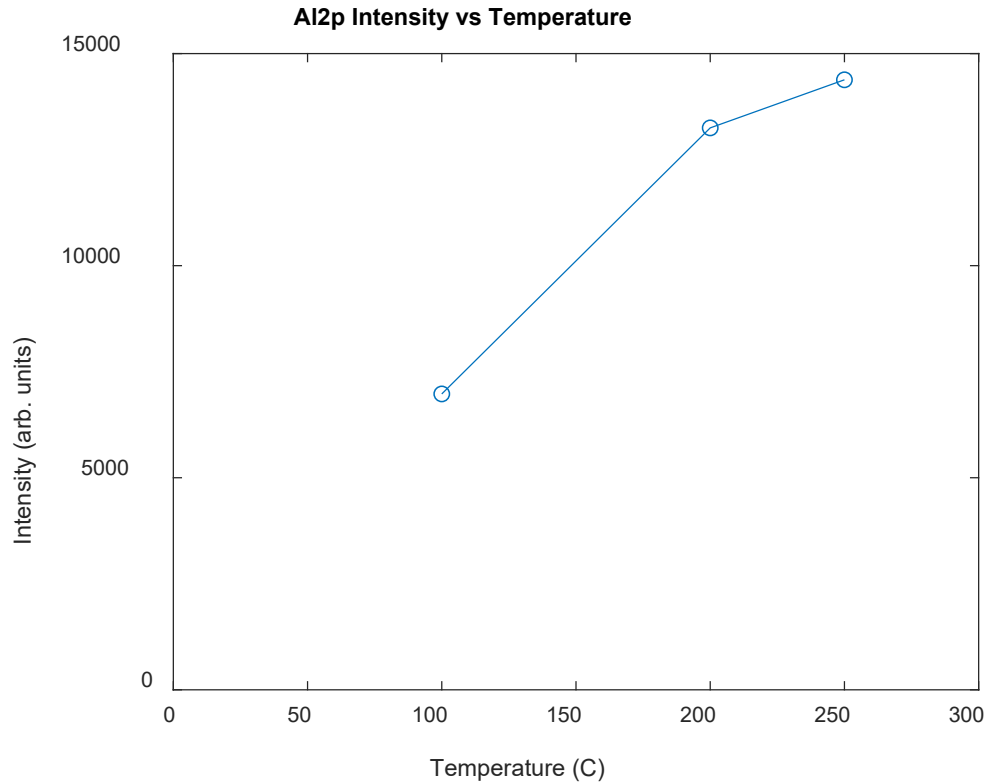


Precursor Diffusion/Reaction in PMMA

- Precursors such as trimethylaluminum (TMA) diffuse in PMMA²



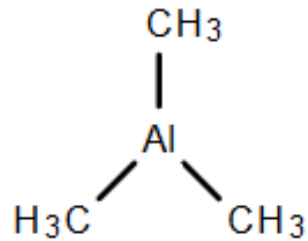
Effects of ALD Process Variables



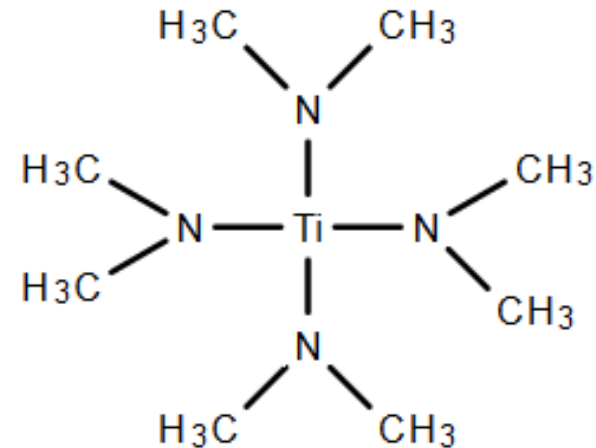
- Temperature and Purge Times have an affect on alumina in PMMA
- There's still alumina in PMMA (1000 arb. units is significant)

Changing Precursors/Material

- Other ALD processes are more selective on spin-coated PMMA²
 - Changed deposited material
 - *HfO₂, Pt, TiO₂*



Trimethylaluminum

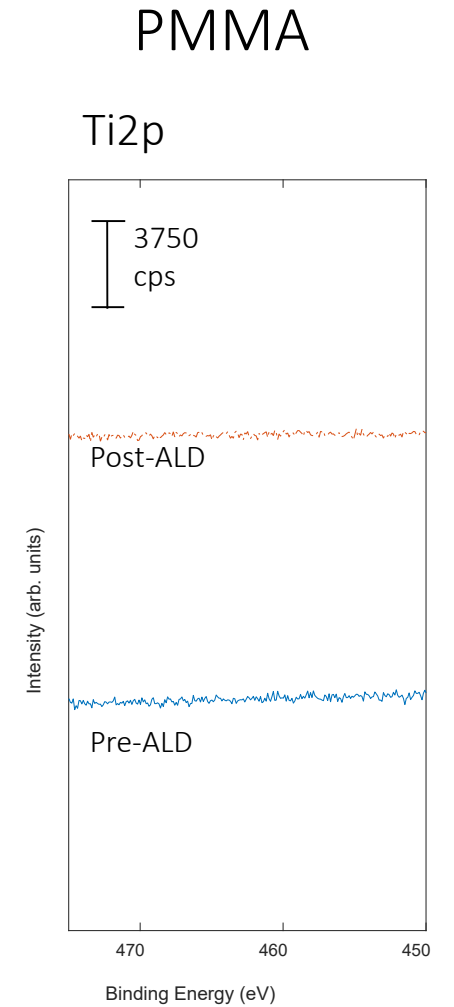
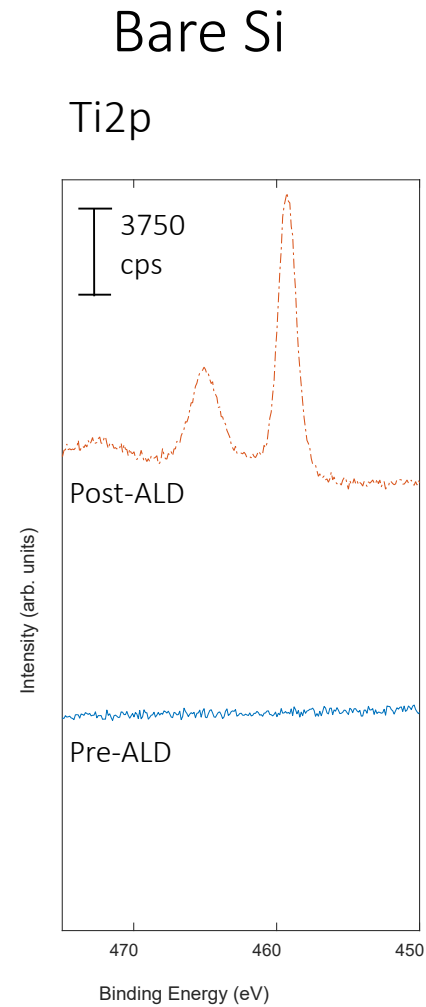


Tetrakis(dimethylamido) Titanium

TiO₂ ALD on PMMA

TiO₂ Deposition on bare Si

Grown PMMA has no significant Ti



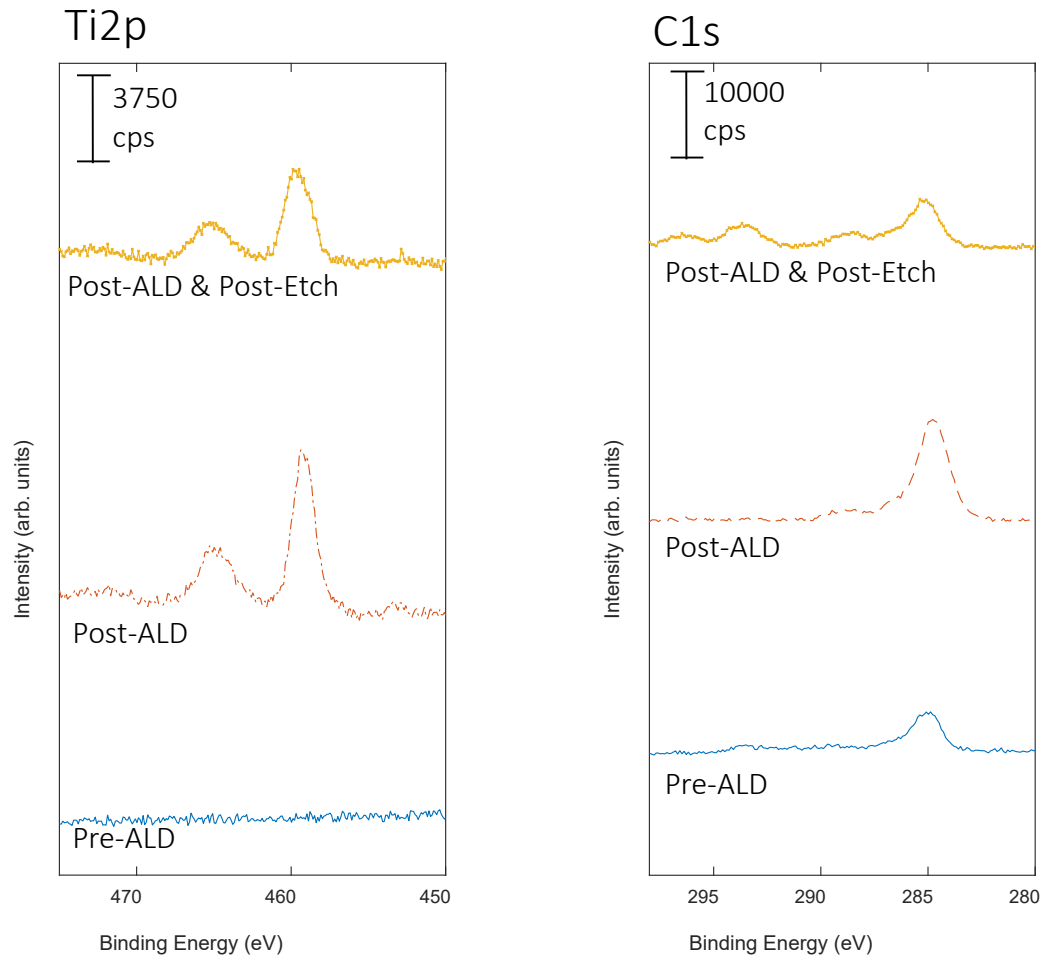
Selective Etching of Grown PMMA Brush

After AS-ALD, want to remove PMMA mask while keeping deposited material

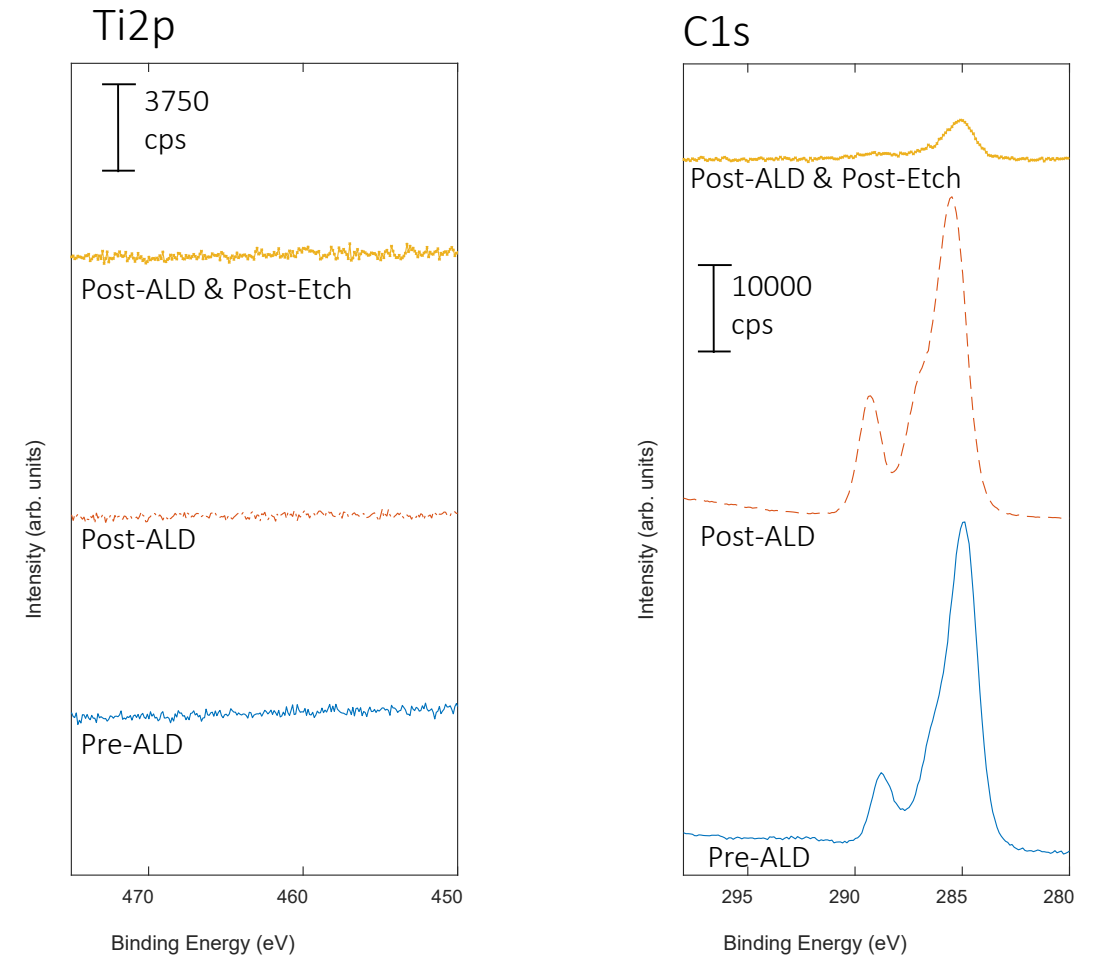
- Wet Chemical Etching
 - Piranha Solution
 - Standard Clean-1 Solution
- Dry Etching
 - O₂ Plasma

O₂ Plasma Etch

Bare Si



PMMA



O₂ Plasma selectively etches PMMA, but not TiO₂

Conclusions

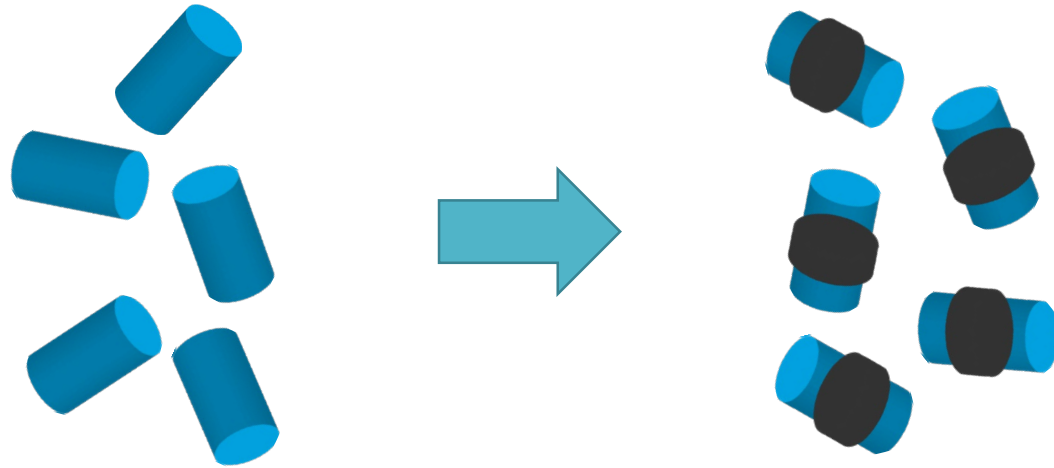
Main factors in grown PMMA brush effectiveness as a mask

1. Precursor Size/Chemistry (**Major**)
2. Temperature (**Minor**)
3. Purge times (**Minor**)

PMMA can be selectively etched off without significant damage to deposited oxide using O₂ plasma

Future Plans

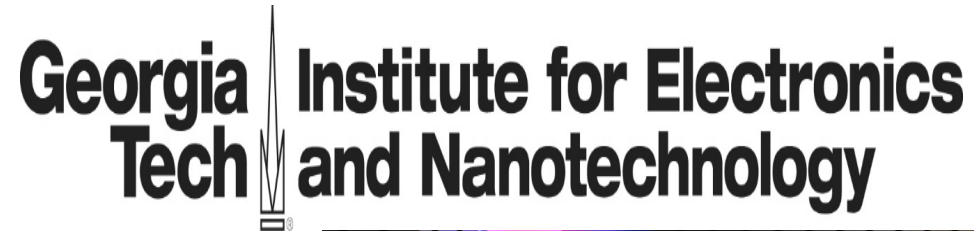
- Use a bulkier precursor for alumina ALD
- Test on nanowires
 - Repeat what I've done on substrates with nanowires
- Implement SCALES & AS-ALD to create functioning 3D nanodevices



Acknowledgments

Thanks to

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- NSF
 - NSF EEC-1757579
- SUIN REU
 - Leslie O'Neill & Dr. Quinn Spadola
- Cornell
 - Melanie-Claire Mallison



QUESTIONS?

Citations (Paper)

- (1) Mohabir, A. T.; et. al. Bottom-Up Masking of Si / Ge Surfaces and Nanowire Heterostructures via Surface Initiated Polymerization and Selective Etching. No. 2.
- (2) Färm, E.; Kemell, M.; Ritala, M.; Leskelä, M. Selective-Area Atomic Layer Deposition Using Poly(Methyl Methacrylate) Films as Mask Layers. *J. Phys. Chem. C* **2008**, *112* (40), 15791–15795. <https://doi.org/10.1021/jp803872s>.
- (3) Mamei, A.; Merkx, M. J. M.; Karasulu, B.; Roozeboom, F.; Kessels, W. E. M. M.; MacKus, A. J. M. Area-Selective Atomic Layer Deposition of SiO₂ Using Acetylacetone as a Chemoselective Inhibitor in an ABC-Type Cycle. *ACS Nano* **2017**, *11* (9), 9303–9311. <https://doi.org/10.1021/acsnano.7b04701>.
- (4) Hobbs, R. G.; Petkov, N.; Holmes, J. D. Semiconductor Nanowire Fabrication by Bottom-Up and Top-Down Paradigms. *Chem. Mater.* **2012**, *24* (11), 1975–1991. <https://doi.org/10.1021/cm300570n>.

Citations (Paper)

- (5) Namazi, L.; Nilsson, M.; Lehmann, S.; Thelander, C.; Dick, K. A. Selective GaSb Radial Growth on Crystal Phase Engineered InAs Nanowires. *Nanoscale* **2015**, 7 (23), 10472–10481. <https://doi.org/10.1039/C5NR01165E>.
- (6) Mackus, A. J. M.; Merkx, M. J. M.; Kessels, W. M. M. From the Bottom-Up: Toward Area-Selective Atomic Layer Deposition with High Selectivity. *Chem. Mater.* **2019**, 31 (1), 2–12. <https://doi.org/10.1021/acs.chemmater.8b03454>.
- (7) Johnson, R. W.; Hultqvist, A.; Bent, S. F. A Brief Review of Atomic Layer Deposition: From Fundamentals to Applications. *Materials Today*. 2014. <https://doi.org/10.1016/j.mattod.2014.04.026>.

Citations (Image)

- https://www.adafruit.com/product/976?main_page=product_info&products_id=976
- <http://www.lithoguru.com/scientist/lithobasics.html>
- Su'ait, M. S.; Noor, S. A. M.; Ahmad, A.; Hamzah, H.; Rahman, M. Y. A. Preparation and Characterization of Blended Solid Polymer Electrolyte 49% Poly(Methyl Methacrylate)-Grafted Natural Rubber:Poly(Methyl Methacrylate)–Lithium Tetrafluoroborate. *J. Solid State Electrochem.* **2012**, *16* (6), 2275–2282. <https://doi.org/10.1007/s10008-011-1637-8>.

Citations (image)

- Dong, W.; Zhang, K.; Zhang, Y.; Wei, T.; Sun, Y.; Chen, X.; Dai, N. Application of Three-Dimensionally Area-Selective Atomic Layer Deposition for Selectively Coating the Vertical Surfaces of Standing Nanopillars. *Sci. Rep.* **2015**, *4* (1), 4458. <https://doi.org/10.1038/srep04458>.
- Storm, K.; Nylund, G.; Samuelson, L.; Micolich, A. P. Realizing Lateral Wrap-Gated Nanowire FETs: Controlling Gate Length with Chemistry Rather than Lithography. *Nano Lett.* **2012**, *12* (1), 1–6. <https://doi.org/10.1021/nl104403g>.
- Minaye Hashemi, F. S.; Prasittichai, C.; Bent, S. F. Self-Correcting Process for High Quality Patterning by Atomic Layer Deposition. *ACS Nano* **2015**, *9* (9), 8710–8717. <https://doi.org/10.1021/acsnano.5b03125>.